

HOPELEX TC-8001A

Polycarbonate compound resin

General Information

Description

Thermal conductive, 30% mineral filled
Medium viscosity, easy mold release
Available in opaque color only

Applications

Heat sinks, cooling units, electric/electronic housings, etc.

Typical properties¹

	Test Method	Typical value	Unit
Physical			
Melt Flow Index, 300 °C, 1.2 kg	ASTM D1238	20	g/10min
Specific Gravity	ASTM D792	1.52	
Mold Shrinkage	HPC method	0.4 ~ 0.6	%
Mechanical			
Tensile Strength, yield, 50 mm/min	ASTM D638	430	kg _f /cm ²
Tensile Elongation, break, 50 mm/min	ASTM D638	-	%
Flexural Strength, yield, 10 mm/min	ASTM D790	560	kg _f /cm ²
Flexural Modulus, 10 mm/min	ASTM D790	26,000	kg _f /cm ²
IZOD Impact Strength, notched, 23 °C, 1/8"	ASTM D256	3	kg _f ·cm/cm
	ASTM D256	-	kg _f ·cm/cm
Thermal			
Thermal conductivity	Hot-wire method	0.6	W/m·K
Heat Distortion Temp. 4.6 kg _f /cm ²	ASTM D648	-	°C
	ASTM D648	140	°C
Vicat Softening Temp. Rate B/50	ASTM D1525	-	°C

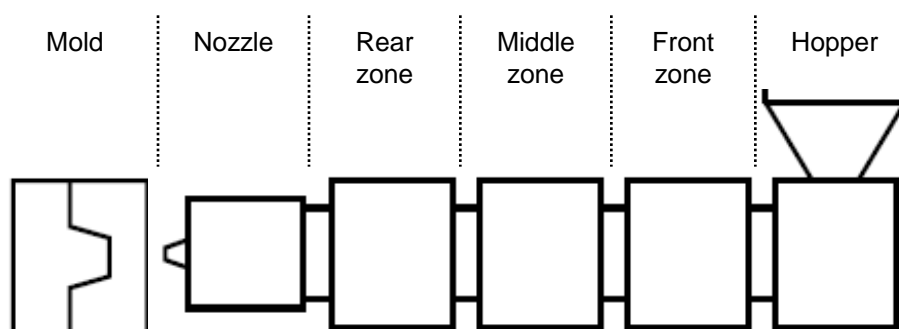
Notes

ISO 9001, 14001, /TS 16949

¹ Typical properties : these are not to be construed as specifications.

Processing guides¹

	Typical value	Unit
Drying condition		
Drying temperature	120	°C
Drying time	4	hr
Maximum moisture content	0.02	%
Injection molding		
Melt temperature	290 ~ 310	°C
Nozzle temperature	280 ~ 300	°C
Barrel	Rear zone	290 ~ 310
	Middle zone	280 ~ 300
	Front zone	270 ~ 290
Hopper temperature	60 ~ 80	°C
Mold temperature	60 ~ 90	°C



Recycling

Sprues and runners can be reground with virgin resin within the ratio of 20%. Care must be taken to ensure that the regrind is free from impurities and regrind should not be used in applications where impact performance and/or agency compliance are required.

Notes

ISO 9001, 14001, /TS 16949

¹ Processing guides : Typical processing parameters are noted. Actual processing conditions will depend on machine size, mold design, material residence time, shot size, etc.